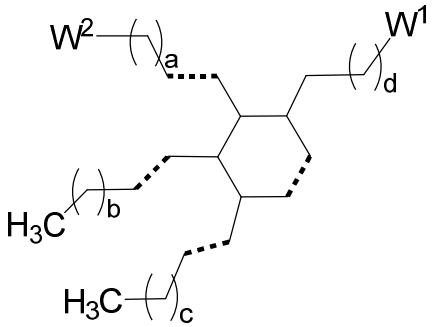
CLAIMS

1. A photosensitive resin composition comprising a polyfunctional monomer (A), a binder resin (B), and a photopolymerization initiator (C),

wherein the polyfunctional monomer (A) contains a compound represented by expression (1), and the binder resin (B) contains one or more substance selected from the group consisting of a polyimide, a polyimide precursor, a polybenzoxazole, a polybenzoxazole precursor, a polyamide, a copolymer thereof, a polyurea, a polyester, a polysiloxane, an acrylic resin, a phenol resin, a benzocyclobutene resin, a maleic acid resin, and a cycloolefin polymer,

[Chem. 1]



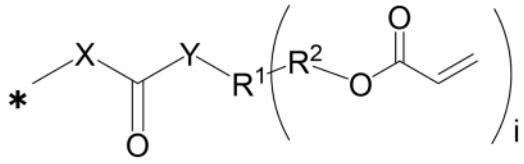
(1)

wherein, in expression (1), W^1 and W^2 each independently represent a monovalent organic group having a carbon-carbon double bond and 2 to 25 carbon atoms, and a, b, c, and d are natural numbers each independently satisfying a + b = 6 to 17 and c + d = 8 to 19, and the

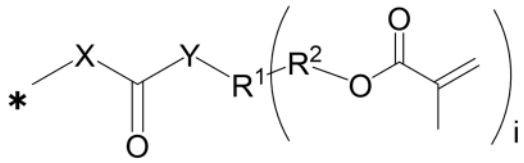
broken line part means a carbon-carbon single bond or a carbon-carbon double bond,

wherein in expression (1), at least one of W^1 and W^2 are groups represented by expression (3), or expression (4),

[Chem. 3]



(3)

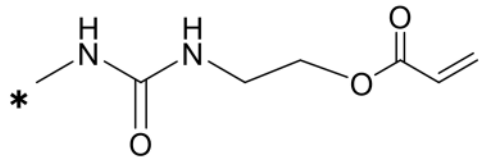


(4)

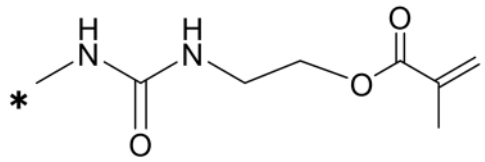
wherein, in expression (3), and expression (4), X and Y are -NH-, R^1 represents a single bond or a 2 to 6 valent organic group having 1 to 5 carbon atoms, R^2 represents a single bond or a divalent organic group having 1 to 5 carbon atoms, i represents an integer 1 to 5, and a sign of * indicates a point of bonding.

2. The photosensitive resin composition according to claim 1, wherein in expression (1), at least one of W^1 and W^2 are groups represented by expression (8), expression (9), expression (10) or expression (11),

[Chem. 5]

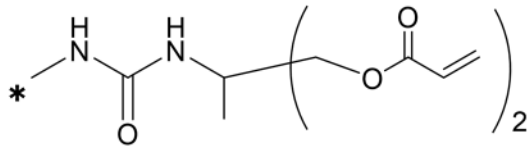


(8)



(9)

[Chem. 6]



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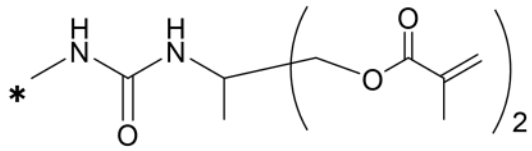


(11)

wherein a sign of * indicates a point of bonding.

3. The photosensitive resin composition according to claim 1, wherein the binder resin (B) contains one or more substance selected from the group consisting of a polyimide, a polyimide precursor, a polybenzoxazole, a polybenzoxazole precursor, a copolymer thereof, and a maleic acid resin.

4. The photosensitive resin composition according to claim 3, wherein the binder resin (B) contains one or more

substance selected from the group consisting of a polyimide, a polyimide precursor, a polybenzoxazole, a polybenzoxazole precursor, and a copolymer thereof, which are obtained by polymerizing a dimer acid derivative as a monomer.

5. The photosensitive resin composition according to claim 3 or 4, wherein the binder resin (B) further contains a phenol resin having a biphenyl structure.

6. The photosensitive resin composition according to claim 1 to 5, wherein the photosensitive resin composition further contains a crosslinking agent (D), and the crosslinking agent (D) contains one or more substance selected from the group consisting of an epoxy compound, an oxetane compound, and a methylol compound.

7. The photosensitive resin composition according to claim 6, wherein the crosslinking agent (D) contains a methylol compound.

8. A cured film obtained by curing the photosensitive resin composition according to any one of claims 1 to 7.

9. An electronic component comprising the cured film

according to claim 8.

10. An antenna element comprising at least one antenna wiring and the cured film according to claim 8,

wherein the antenna wiring includes at least one selected from the group consisting of a meander-shaped loop antenna, a coil-shaped loop antenna, a meander-shaped monopole antenna, a meander-shaped dipole antenna, or a planar antenna, an occupied area per antenna unit in the antenna wiring is 1000 mm^2 or less, and the cured film is an insulation film that insulates between a ground and the antenna wiring.

11. A semiconductor package comprising at least a semiconductor element, a rewiring layer, a sealing resin, and an antenna wiring,

wherein the antenna wiring includes at least one or more selected from the group consisting of a meander-shaped loop antenna, a coil-shaped loop antenna, a meander-shaped monopole antenna, a meander-shaped dipole antenna, and a microstrip antenna, an occupied area per antenna unit in the antenna wiring is 1000 mm^2 or less, an insulating layer of the rewiring layer and/or the sealing resin includes the cured film according to claim 8, and the sealing resin is between a ground and the antenna wiring.

12. The electronic component according to claim 9 comprising:

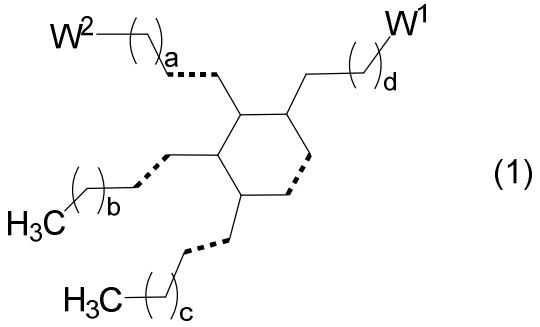
an antenna wiring; and

an antenna element obtained by laminating the cured film according to claim 8,

wherein the antenna wiring has a height of 50 to 200 μm, and the cured film has a thickness of 80 to 300 μm.

13. A compound represented by expression (1),

[Chem. 7]



(1)

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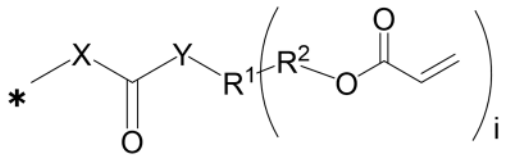
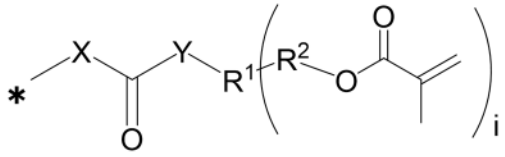
[Chem. 9]



(3)



(4)

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